

NAKAGAWA -
Application No. 10/726,660
Client/Matter: 007324-0307160

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A component mounting circuit board comprising:
a circuit pattern including a plurality of electrically conductive plates, the circuit pattern having two opposite sides;
an inner electrical component electrically connected to one side of the circuit pattern;
and
a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component, the resin molded section having an opening allowing an outer electrical component located outside the resin molded section to be connected to the circuit pattern therethrough,
wherein the circuit pattern includes a portion corresponding to the other side of the inner electrical component and is provided with a thicker metal portion thicker than a remaining portion of said other side of the inner electrical component; and
wherein the thicker metal portion is provided with an exposed portion exposed outside the resin molded section on the other side of the inner electrical component.

2-15 (Canceled)

16. (Previously Presented) A component mounting circuit board comprising:
a circuit pattern including a plurality of electrically conductive plates, the circuit pattern having two opposite sides;
an inner electrical component electrically connected to one side of the circuit pattern;
and
a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component, the resin molded section having an opening allowing an outer electrical component located outside the resin molded section to be connected to the circuit pattern therethrough,

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wherein the circuit pattern includes a portion corresponding to the other side of the inner electrical component and is provided with a thicker metal portion thicker than a remaining portion of said other side of the inner electrical component; and

wherein the thicker metal portion is embedded in the resin molded section and the resin molded section includes a portion located outside the thicker metal portion, said portion being thinner than a remaining portion of the resin molded section on the other side of the inner electrical component.